

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage	100	V
V _{GS}	Gate-source voltage	±20	V
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25 °C	180	Α
I _D ⁽¹⁾	Drain current (continuous) at T _c = 100 °C	180	Α
I _{DM} ⁽²⁾	Drain current (pulsed)	720	А
P _{TOT}	Total dissipation at T _C = 25 °C	315	W
	Derating factor	2.1	W/°C
E _{AS} (3)	Single pulse avalanche energy	1	J
T _j	Operating junction temperature range	-55 to 175	°C
T _{stg}	Storage temperature range		C

- 1. Current limited by package.
- 2. Pulse width limited by safe operating area.
- 3. Starting T_j =25 °C, I_D =60 A, V_{DD} =50 V

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R _{thJC}	Thermal resistance, junction-to-case	0.48	°C/W
R _{thJB} (1)	Thermal resistance, junction-to-board	35	°C/W

1. When mounted on 1 inch² FR-4, 2 Oz copper board.

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2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 3. On/Off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 250 μA, V _{GS} = 0 V	100			V
	Zero gate voltage	V _{GS} = 0 V, V _{DS} = 100 V			1	μA
I _{DSS}	drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V},$ $T_{C} = 125 \text{ °C} ^{(1)}$			100	μА
I _{GSS}	Gate-body leakage current	V _{GS} = ±20 V, V _{DS} = 0 V			100	nA
V _{GS(th)}	Gate threshold voltage	V_{DS} = V_{GS} , I_D = 250 μA	2.5	3.5	4.5	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 60 A		2.1	2.3	mΩ

^{1.} Defined by design, not subject to production test.

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance	V = 25 V f = 1 MHz	-	12800	-	pF
C _{oss}	Output capacitance	$V_{DS} = 25 \text{ V, f} = 1 \text{ MHz,}$ $V_{GS} = 0 \text{ V}$	-	3500	-	pF
C _{rss}	Reverse transfer capacitance	VGS - 0 V	-	170	-	pF
Qg	Total gate charge	V _{DD} = 50 V, I _D = 180 A,	-	180	-	nC
Q _{gs}	Gate-source charge	V _{GS} = 0 to 10 V	-	78	-	nC
Q _{gd}	Gate-drain charge	(see Figure 15. Test circuit for gate charge behavior)	-	34	-	nC

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	V_{DD} = 50 V, I_{D} = 90 A, R_{G} = 4.7 Ω , V_{GS} = 10 V (see Figure 14. Test circuit for resistive load switching times and Figure 19. Switching time waveform)	-	62	-	ns
t _r	Rise time		-	108	-	ns
t _{d(off)}	Turn-off delay time		-	148	-	ns
t _f	Fall time		-	40	-	ns

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		180	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		720	Α
V _{SD} ⁽²⁾	Source-drain curren	I _{SD} = 60 A, V _{GS} = 0 V	-		1.5	V

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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{rr}	Reverse recovery time	I _{SD} = 180 A, di/dt = 100 A/μs	-	85		ns
Q _{rr}	Reverse recovery charge	V _{DD} = 80 V, T _J = 150 °C	-	200		nC
I _{RRM}	Reverse recovery current	(see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	4.7		А

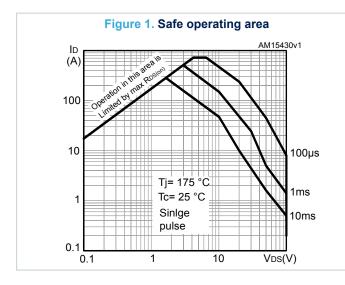
^{1.} Pulse width limited by safe operating area.

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^{2.} Pulsed: pulse duration=300 μs, duty cycle 1.5%.



2.1 Electrical characteristics (curves)



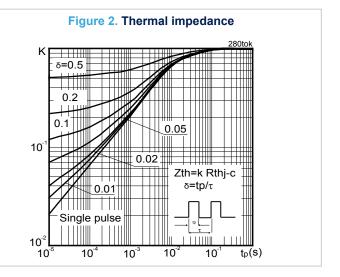
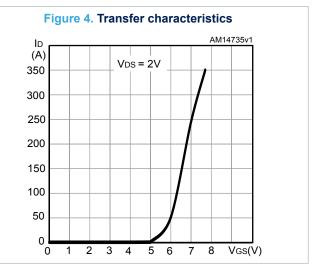
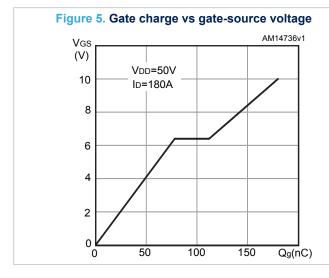
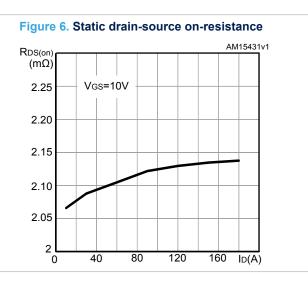


Figure 3. Output characteristics AM14734v1 Vgs=10V (A) 300 8V 7V 250 200 150 100 6٧ 50 5V 0 2 4 6 8 VDS(V) 0







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Figure 7. Normalized V_{(BR)DSS} vs temperature

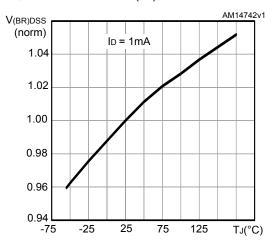


Figure 8. Capacitance variations

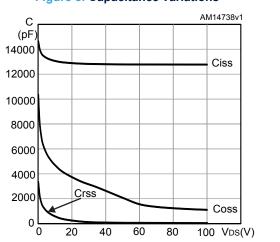


Figure 9. Source-drain diode forward characteristics

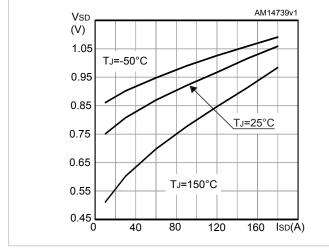


Figure 10. Normalized gate threshold voltage vs temperature

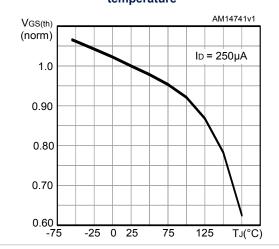
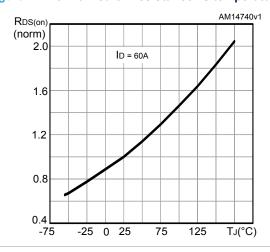


Figure 11. Normalized on-resistance vs temperature



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3 Test circuits

Figure 12. Test circuit for resistive load switching times

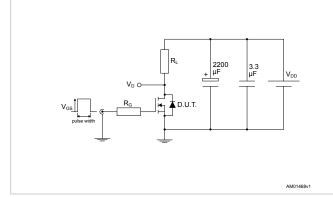


Figure 14. Test circuit for inductive load switching and diode recovery times

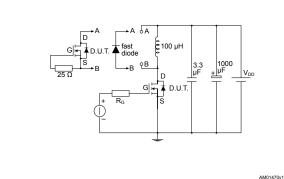


Figure 15. Unclamped inductive load test circuit

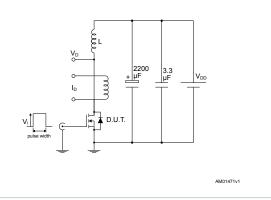


Figure 16. Unclamped inductive waveform

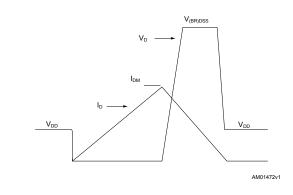
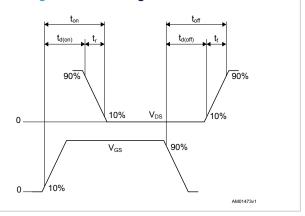


Figure 17. Switching time waveform



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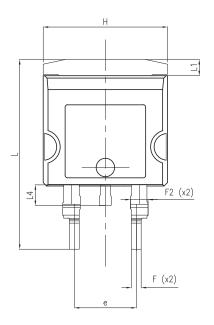


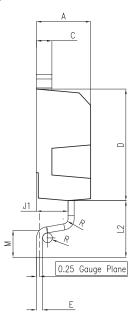
4 Package information

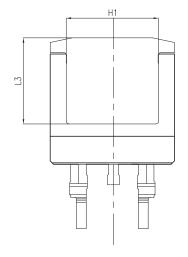
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

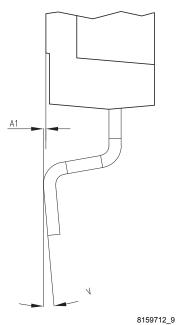
4.1 H²PAK-2 package information

Figure 18. H²PAK-2 package outline









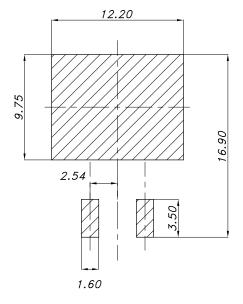
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Table 7. H²PAK-2 package mechanical data

Dim.		mm				
DIM.	Min.	Тур.	Max.			
А	4.30		4.70			
A1	0.03		0.20			
С	1.17		1.37			
D	8.95		9.35			
е	4.98		5.18			
E	0.50		0.90			
F	0.78		0.85			
F2	1.14		1.70			
Н	10.00		10.40			
H1	7.40	-	7.80			
J1	2.49		2.69			
L	15.30		15.80			
L1	1.27		1.40			
L2	4.93		5.23			
L3	6.85		7.25			
L4	1.50		1.70			
M	2.60		2.90			
R	0.20		0.60			
V	0°		8°			

Figure 19. H²PAK-2 recommended footprint



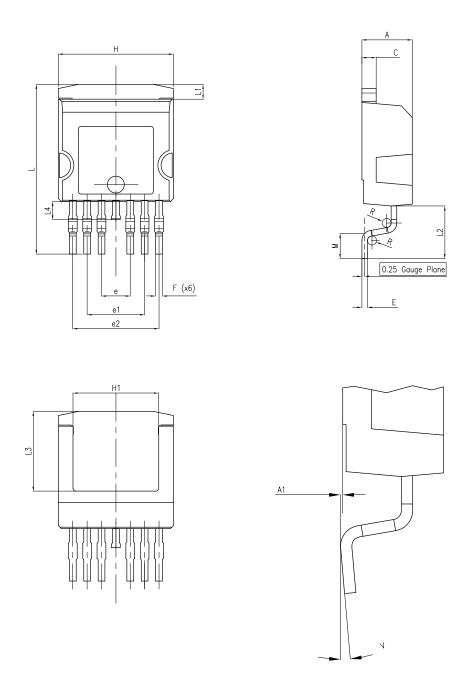
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Note: Dimensions are in mm.



4.2 H²PAK-6 package information

Figure 20. H²PAK-6 package outline



8159693_Rev_8



Table 8. H²PAK-6 package mechanical data

Div	mm				
Dim.	Min.	Тур.	Max.		
А	4.30		4.70		
A1	0.03		0.20		
С	1.17		1.37		
е	2.34	2.54	2.74		
e1	4.88		5.28		
e2	7.42		7.82		
Е	0.45		0.60		
F	0.50		0.70		
Н	10.00		10.40		
H1	7.40		7.80		
L	14.75		15.25		
L1	1.27		1.40		
L2	4.35		4.95		
L3	6.85		7.25		
L4	1.50		1.75		
M	1.90		2.50		
R	0.20		0.60		
V	0°		8°		

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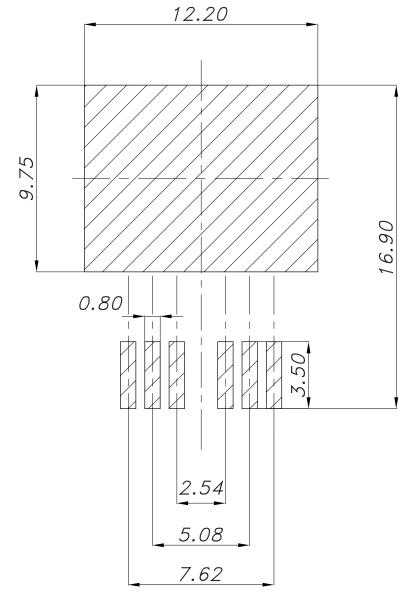


Figure 21. H²PAK-6 recommended footprint

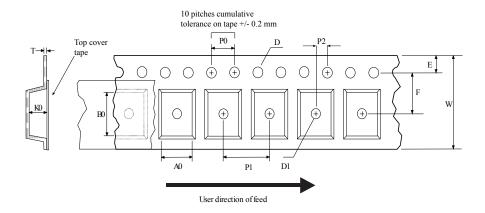
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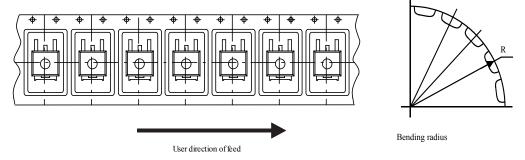
Note: Dimensions are in mm.



4.3 Packing information

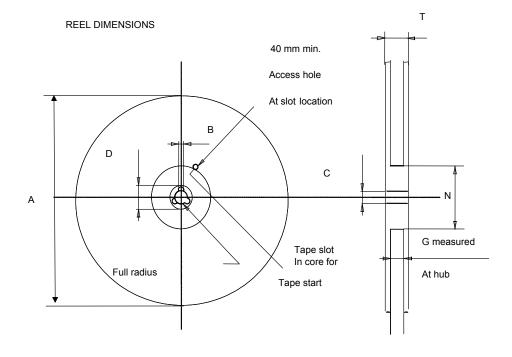
Figure 22. Tape outline





AM08852v2

Figure 23. Reel outline



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Table 9. Tape and reel mechanical data

	Таре			Reel			
Dim.	n	nm	Dis.	mm			
Dim.	Min.	Max.	Dim.	Min.	Max.		
A0	10.5	10.7	А		330		
В0	15.7	15.9	В	1.5			
D	1.5	1.6	С	12.8	13.2		
D1	1.59	1.61	D	20.2			
Е	1.65	1.85	G	24.4	26.4		
F	11.4	11.6	N	100			
K0	4.8	5.0	Т		30.4		
P0	3.9	4.1					
P1	11.9	12.1	Base q	uantity	1000		
P2	1.9	2.1	Bulk quantity		1000		
R	50						
Т	0.25	0.35					
W	23.7	24.3					



Revision history

Table 10. Document revision history

Date	Version	Changes
02-Aug-2013	1	Initial release.
03-Sep-2013	2	Modified: <i>Table 1</i>, RDS(on) typical value in <i>Table 4</i>Minor text changes
27-May-2014	3	 Modified: title and Features in cover page Updated: Section 4: Package mechanical data Minor text changes
12-Sep-2014	4	- Modified: title, features and description in cover page.
03-May-2021	5	Updated Table 1. Absolute maximum ratings. Minor text changes.



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